METHOD OF MANUFACTURING WAFER CARRIER

Abstract of the Disclosure

Provided is a method of manufacturing a wafer carrier capable of providing good abrasion resistance to remarkably increase lifespan of the wafer carrier, and preventing occurrence of defects from an edge of a wafer during double-sided polishing of the wafer. The method includes machining a carrier body constituting the wafer carrier in a pre-set shape, forming a preliminary hole and a slurry introduction hole in the carrier body of the wafer carrier, coating diamond-like carbon (DLC) on the carrier body having the preliminary hole, and, after coating the DLC, enlarging the preliminary hole to form a wafer retaining hole, into which the wafer is inserted.

Fig 4